

## Part Number: XZCBD55W-A2RT

3.2x1.6mm SMD CHIP LED LAMP

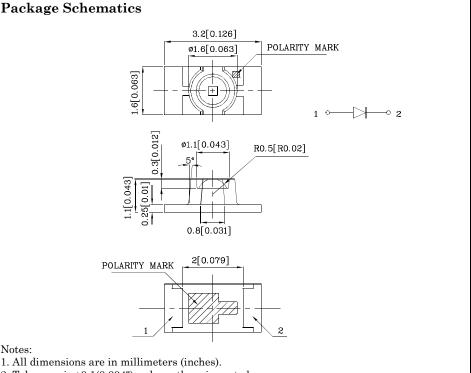
### **Features**

- Ideal for indication light on hand held products
- Long life and robust package
- Standard Package: 2,000pcs/ Reel
- MSL (Moisture Sensitivity Level): 3
- RoHS compliant





ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES



2. Tolerance is  $\pm 0.1(0.004")$  unless otherwise noted.

Notes:

3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T <sub>A</sub> =25°C)	Blue (InGaN)	Unit			
Reverse Voltage	$V_{\mathrm{R}}$	5	V		
Forward Current	$\mathbf{I}_{\mathbf{F}}$	30	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA		
Power Dissipation	$\mathbf{P}_{\mathrm{D}}$	120	mW		
Electrostatic Discharge Threshold (HBM)	250	V			
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C		
Storage Temperature	Tstg	-40 ~ +85	-0		

Operating Characteristics (T <sub>A</sub> =25°C)		Blue (InGaN)	Unit	
Forward Voltage (Typ.) (I <sub>F</sub> =20mA)	$V_{\rm F}$	3.3	V	
Forward Voltage (Max.) (I <sub>F</sub> =20mA)	$V_{\mathrm{F}}$	4	V	
Reverse Current (Max.) (V <sub>R</sub> =5V)	$I_R$	50	uA	
Wavelength of Peak Emission CIE127-2007*(Typ.) (I <sub>F</sub> =20mA)	λP	460*	nm	
Wavelength of Dominant Emission CIE127-2007*(Typ.) $(I_F=20mA)$	λD	465*	nm	
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =20mA)	$ riangle\lambda$	25	nm	
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	100	pF	

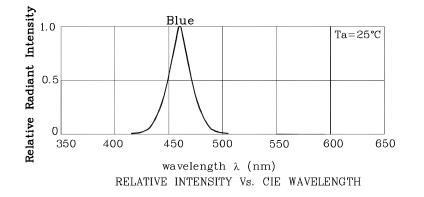
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous CIE127 (I <sub>F</sub> =20 m	7-2007* 0mA)	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZCBD55W-A2RT	Blue	InGaN	Water Clear	120*	248*	460*	70°

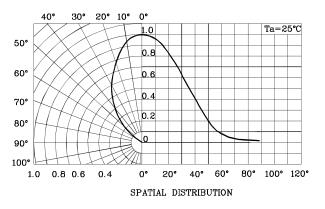
\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Nov 20,2015

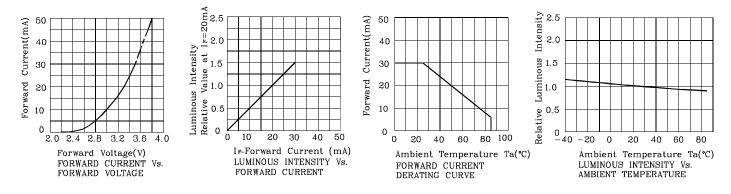
XDSB3962 V4-Z Layout: Maggie L.





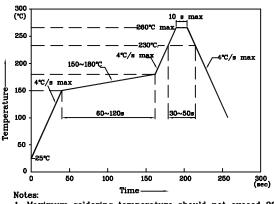


### ✤ Blue



# LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

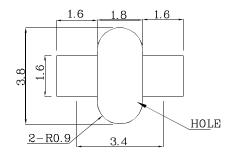


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C 3. Do not put stress to the epoxy resin during
- high temperatures conditions

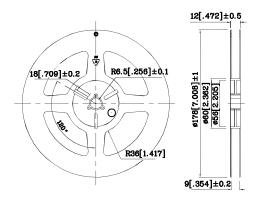


The device has a single mounting surface. The device must be mounted according to the specifications.

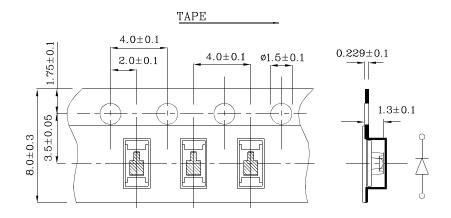
## Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



# Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

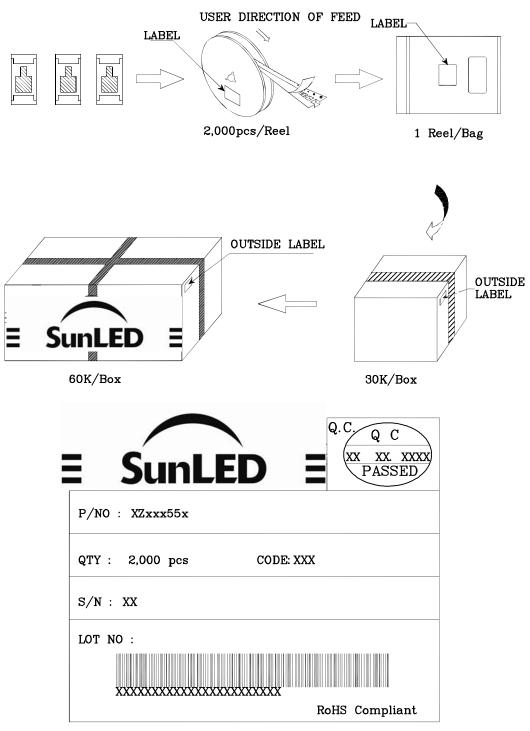
2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V  $\,$ 

Note: Accuracy may depend on the sorting parameters.



### PACKING & LABEL SPECIFICATIONS



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